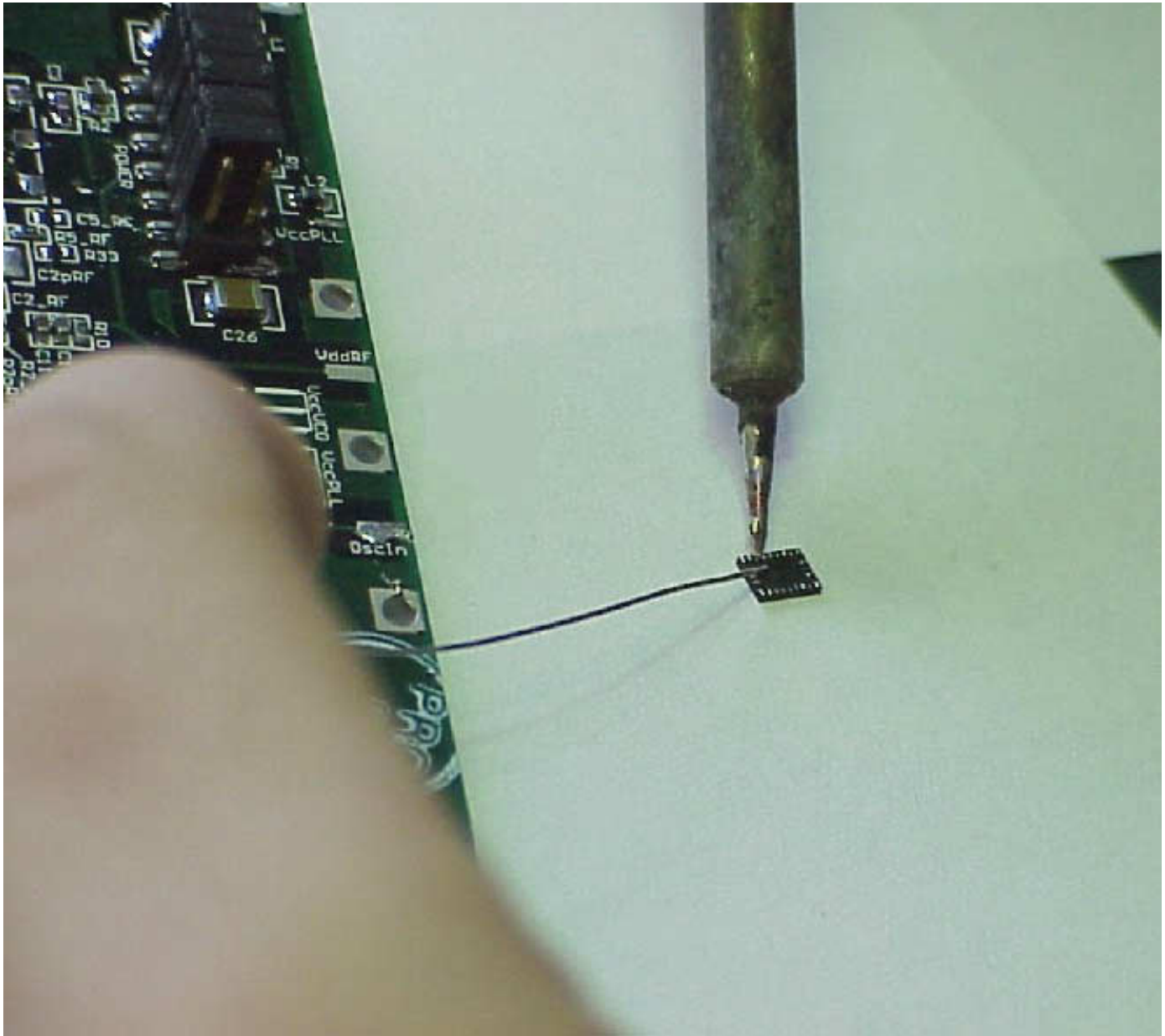


Figure 2



Prepare the pads on the pc board and on CSP and LLP packages by tinning them with a small amount of solder.